



## PRODUCT DATA SHEET



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**Datasheet**



**Resources**



**Samples**

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.jg-semi.cn](http://www.jg-semi.cn). Please email any questions regarding the system integration to [JINGAO\\_questions@jgsemi.com](mailto:JINGAO_questions@jgsemi.com).

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
20V	190mΩ@4.5V	0.75A
	260mΩ@2.5V	
	390mΩ@1.8V	

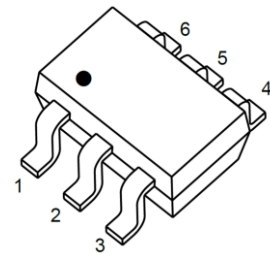
### Feature

- Surface Mount Package
- N-Channel Switch with Low  $R_{DS(on)}$
- Operated at Low Logic Level Gate Drive

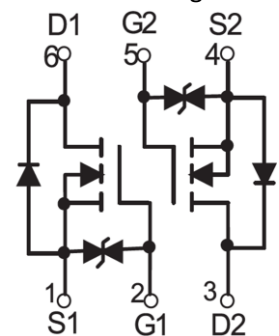
### Application

- Load/Power Switching
- Interfacing Switching
- Battery Management for Ultra Small Portable Electronics
- Logic Level Shift

SOT-363



Schematic diagram



### ABSOLUTE MAXIMUM RATINGS ( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>(1)</sup>	$I_D$	0.75	A
Power Dissipation <sup>(1)</sup>	$P_D$	150	mW
Thermal Resistance from Junction to Ambient <sup>(1)</sup>	$R_{\theta JA}$	833	$^{\circ}\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^{\circ}\text{C}$

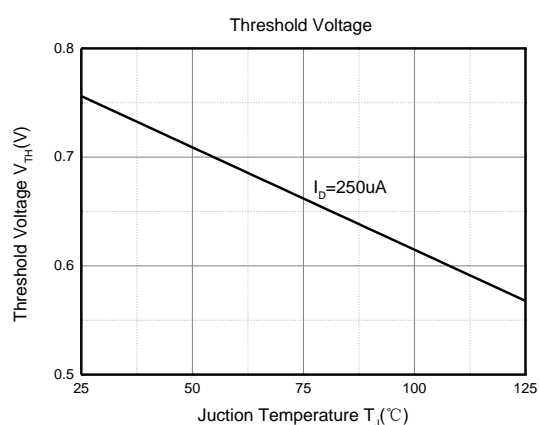
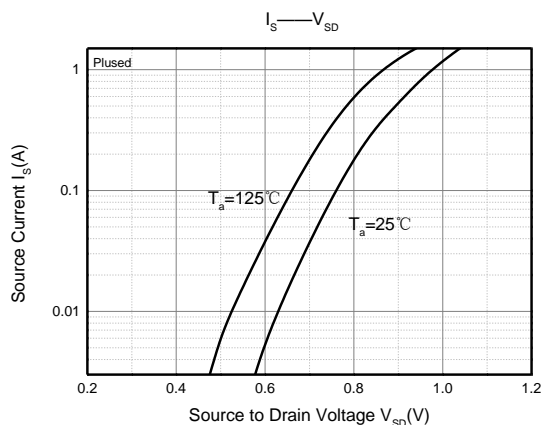
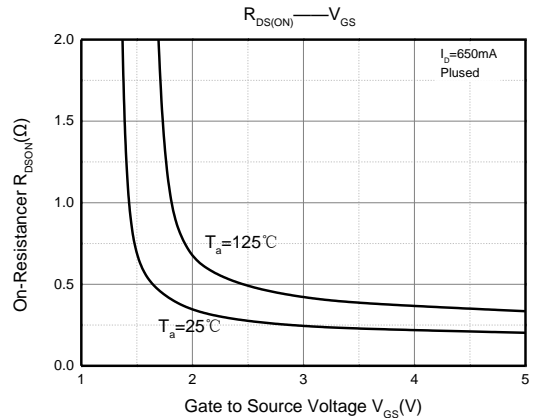
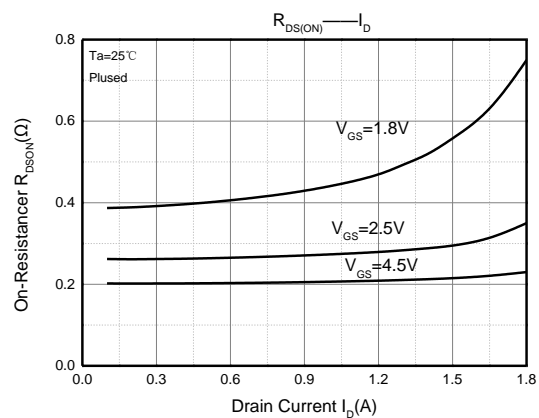
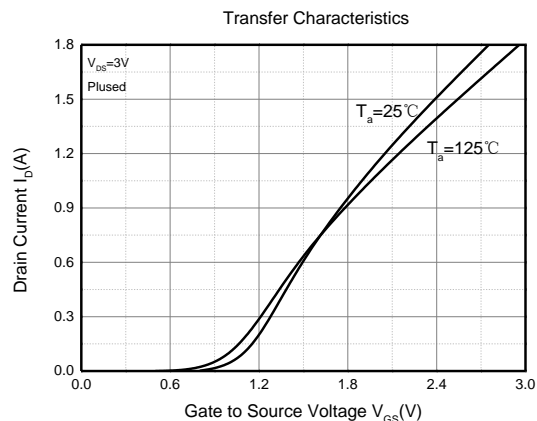
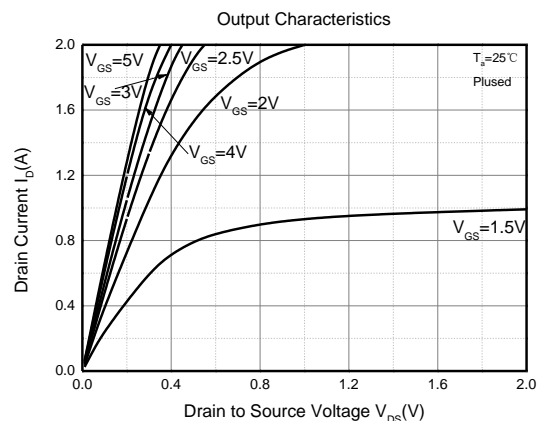
**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

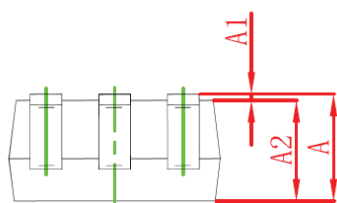
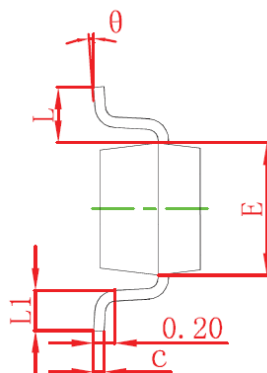
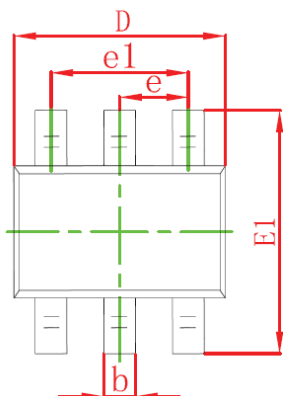
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	20			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> = 0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±10V, V <sub>DS</sub> = 0V			±20	μA
Gate threshold voltage <sup>(1)</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.35	0.75	1.1	V
Drain-source on-resistance <sup>(1)</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =650mA		190	260	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =550mA		260	360	
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =450mA		390	590	
Forward tranconductance <sup>(1)</sup>	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =800mA		1.6		S
Dynamic characteristics <sup>(2)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, f=1MHz			120	pF
Output Capacitance	C <sub>oss</sub>				20	
Reverse Transfer Capacitance	C <sub>rss</sub>				15	
Switching Characteristics <sup>(2)</sup>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =500mA, V <sub>GS</sub> =4.5V, R <sub>G</sub> =10Ω		6.7		ns
Turn-on rise time	t <sub>r</sub>			4.8		
Turn-off delay time	t <sub>d(off)</sub>			17.3		
Turn-off fall time	t <sub>f</sub>			7.4		
Source-Drain Diode characteristics						
Diode Forward voltage <sup>(1)</sup>	V <sub>DS</sub>	I <sub>S</sub> =0.15A, V <sub>GS</sub> = 0V			1.2	V

**Notes:**

1. Pulse Test : Pulse width ≤ 300μs, duty cycle ≤ 0.5%.
2. Guaranteed by design, not subject to production testing

## Typical Electrical and Thermal Characteristics



**SOT-363 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

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